QUALITEK®

326F Flux
Low Solids, No-Clean

DESCRIPTION

326F no-clean flux is a homogeneous mixture of halogen-free, low solids flux developed to meet the industry's need for high speed automation and high reliability. 326F exhibits excellent wetting and fluxing characteristics with essentially no post-soldering residue. 326F eliminates the expense of cleaning without surface insulation resistance degradation.

BENEFITS

- Halide Free
- Excellent wetting on virtually all types of substrates
- Drops in to most operations without process changes
- Rosin/Resin free

APPLICATION METHODS

326F no-clean flux may be applied by foam, spray, or wave methods. Flux deposition, density, and uniformity are critical to successful use of low solids no-clean flux. After foam or wave application, an air knife should be used to remove excess flux from the assembly. Pre-heating the assembly will partially volatilize the solvents, enhance oxide removal, and promote optimum wicking and solder joint formation. The optimum pre-heat temperature range is 90^{O}–110^{O}C (194^{O}-230^{O}F) on the top side of the assembly.

PACKAGING & STORAGE

326F flux is available in 1, 5 and 55 gallon containers. It should be stored in cool, dry place away from ignition sources.

PHYSICAL & CHEMICAL CHARACTERISTICS

Color and Appearance	Colorless Liquid
Solids Content, % (By Wt.)	1.7 – 2.3
Specific Gravity	0.806 +/- 0.005
Flash Point	53°F
Surface Insulation Resistance-Ohms	
J-STD-004	$>1.00 \times 10^{9}$
Acid Number	17.0 – 20.0
Flux Classification per J-STD-004	ORL0
Copper Mirror Test	Pass (No complete breakthrough)
Silver Chromate Test	
Chloride and Bromide	Pass (No discoloration)
Spot Test (Flouride)	Pass (No color change)
Corrosion Test	Pass (No evidence of corrosion)
Shelf life (un-opened)	2 years

PROCESS CONTROL

Control of the flux is necessary to ensure a consistent amount of flux is applied to assemblies. Due to the very low solids percentage of no-clean fluxes, specific gravity is not an accurate measure for solids content. Monitoring and controlling acid number is recommended to maintain the proper flux concentration. Titration may be accomplished with the Qualitek HDT-200 Digital Titration Kit. Control of the flux can be achieved with Qualitek 300A thinner. Debris and contaminants will accumulate in the flux reservoir. Periodically, the replacement of the flux is required for consistent soldering performance, and to prevent debris build-up on the circuit assembly. This should be performed every 35-40 hours of operation.

TEL: (630) 628-8083 FAX: (630) 628-6543 E-MAIL: solder@qualitek.com HOME PAGE:http://www.qualitek.com
HEADQUARTERS: 315 Fairbank St., Addison, IL 60101 U.S.A.
WORLDWIDE BRANCHES: UNITED KINGDOM – MEXICO – CHINA – PHILLIPINES - SINGAPORE
QUALITEK INTERNATIONAL, INC. AN ISO 9002 CERTIFIED COMPANY

Rev: 040599-326F

Consult MSDS for health and safety information